2 4 5	Number	Hits 59826	1	DB	Time stamp
		33020	1 DOMASS WITH (MILSS INTERCONNECTES)		
				USPAT; US-PGPUB	2004/05/14 12:38
5		38021	(bond\$3 with (wir\$3 interconnect\$3)) and		lana dan dan dan dan dan dan dan dan dan
5			(remov\$3 detach\$3)	USPAT;	2004/05/14 12:21
		15665	((bond\$3 with (wir\$3 interconnect\$3)) and	US-PGPUB	
	· · ·		(romovice detached)) and	USPAT;	2004/05/14 12:22
			(remov\$3 detach\$3)) and (light x?ray x-ray	US-PGPUB	
6		0767	("x" near3 "ray"))		
o		8767	(((bond\$3 with (wir\$3 interconnect\$3)) and	USPAT;	2004/05/14 12:22
•			(remov\$3 detach\$3)) and (light x2ray v-ray	US-PGPUB	
•		,	("x" near3 "ray"))) and ((second dummy		
	•	4 *	sacrificial temp\$8) near50 (base substrate	1,	
		1	waier))		·
7		6766	((((bond\$3 with (wir\$3 interconnect\$3)) and	HODAM	0004/05/5
			(remov\$3 detach\$3)) and (light x?ray x-ray	USPAT;	2004/05/14 12:19
			("x" near3 "ray"))) and ((second dummy	US-PGPUB	
t		1	sacrificial temp\$8) near50 (base substrate	1.	
	. '	,	wafer))) and (insulat\$3 dielectric)		
8		50503	(bonds) with (wire) interest to		••
		3000	(bond\$3 with (wir\$3 interconnect\$3)) and (remov\$3 detach\$3 separat\$5)	USPAT;	2004/05/14 12:38
9		19768	(/bondes with (wines	US-PGPUB	
_		13700		USPAT;	2004/05/14 12:38
			(remov\$3 detach\$3 separat\$5)) and (light	US-PGPUB	
10		10500	x?ray x-ray ("x" near3 "ray"))	·.	
10		10522	I CONTRACT WELL WITTON INCELCONNECES (II SAM	USPAT;	2004/05/14 12:23
	* .		(remov\$3 detach\$3 separat\$5)) and (light	US-PGPUB	2001,03,11 12.25
	· · · ·		X?ray x-ray ("x" near3 "ray"))) and (/second		
٠.			dummy sacrificial temp\$8) near50 (base		
	,		substrate wafer))		
11		1811	((((bond\$3 with (wir\$3 interconnect\$3)) and	USPAT:	2004/05/14 12:39
		1.	(remov\$3 detach\$3 separat\$5)) and (light	US-PGPUB	2004/05/14 12:39
			X?ray x-ray ("x" near3 "ray"))) and (/gogond	OD-FGFOB	
		•	dummy sacrificial temps8) nears0 (base)	,	~ ;
		*. ·	SUDStrate water))) and ((heats3 irradca)	,	
	. • •		same (remov\$3 detach\$3 separat\$5) same		
		4.	(second dummy sacrificial temp\$8) same (base		
			substrate wafer))		
12		53946	bond\$3 with (wir\$3 interconnect\$3)		
•	.		(	EPO; JPO;	2004/05/14 12:38
				DERWENT;	
13		6594	(bond\$3 with (wir\$3 interconnect\$3)) and	IBM_TDB	ar I i i i i i i i i i i i i i i i i i i
		0331	(remov\$3 detach\$3 separat\$5)	EPO; JPO;	2004/05/14 12:38
		<i>'</i>	(Tellov\$3 decach\$3 separat\$5)	DERWENT;	
14		434	((honds) with (winds)	IBM_TDB	***
_	1	434	((bond\$3 with (wir\$3 interconnect\$3)) and	EPO; JPO;	2004/05/14 12:39
	- 1	- 1	(remov\$3 detach\$3 separat\$5)) and (light	DERWENT;	,,
L5	.	, , ,	x?ray x-ray ("x" near3 "ray"))	IBM TDB	
٠.	į	13	(((bond\$3 with (wir\$3 interconnect\$3)) and	EPO; JPO;	2004/05/14 12:39
			(remov\$3 detach\$3 separat\$5)) and (light	DERWENT;	
	. ; }		X:ray X-ray ("X" near3 "ray"))) and (/hookea	IBM_TDB	
			TITADS6) Same (remov\$3 detach\$3 separates)		· 1
. ,			same (second dummy sacrificial tempss) same		
		<u> </u>	(base substrate wafer))	į	

Page 1